

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
CHII-HORNG LI	07/29/2016
CHIH-SHAN CHEN	07/29/2016
ROGER TAI	07/29/2016
YIH-ANN LIN	07/29/2016
YEN-RU LEE	07/22/2016
TZU-CHING LIN	07/29/2016
RECEIVING PARTY DATA	
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.
Street Address:	8, LI-HSIN RD. 6
Internal Address:	HSINCHU SCIENCE PARK
City:	HSINCHU
State/Country:	TAIWAN
Postal Code:	300-78
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16872235
CORRESPONDENCE DATA	
Fax Number:	(214)200-0853
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	2146515000
Email:	ipdocketing@haynesboone.com
Correspondent Name:	HAYNES AND BOONE,LLP, IP SECTION
Address Line 1:	2323 VICTORY AVENUE
Address Line 4:	DALLAS, TEXAS 75219
ATTORNEY DOCKET NUMBER:	2015-1406/24061.3342US04
NAME OF SUBMITTER:	MARCY OGADO
SIGNATURE:	/Marcy Ogado/
DATE SIGNED:	05/11/2020

Total Attachments: 6

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ASSIGNMENT

WHEREAS, we,

- | | | | |
|-----|----------------|----|--|
| (1) | Chii-Horng Li | of | No. 137, Wencai St., Hsinchu County
Zhubei City 302, Taiwan, R.O.C. |
| (2) | Chih-Shan Chen | of | 9F., No. 101, Jixian Rd. Sanchong Dist.
New Taipei City 24151, Taiwan, R.O.C. |
| (3) | Roger Tai | of | Tainan City, Taiwan, R.O.C. |
| (4) | Yih-Ann Lin | of | No. 21, Lane 66, Fuguei St., Hsinchu County
Jhudong Township 310, Taiwan, R.O.C. |
| (5) | Yen-Ru Lee | of | 9F., No. 539-2, Sec. 2, Jingguo Rd., North Dist.
Hsinchu City 300, Taiwan, R.O.C. |
| (6) | Tzu-Ching Lin | of | Hsinchu City, Taiwan, R.O.C. |

have invented certain improvements in

V-SHAPE RECESS PROFILE FOR EMBEDDED SOURCE/DRAIN EPITAXY

for which we have filed an application for Letters Patent of the United States of America on August 12, 2016, and assigned U.S. Serial number 15/235,899; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Co., Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, Republic of China, is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said

invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Chii-Hong Li

Residence Address: No. 137, Wencai St., Hsinchu County
Zhubei City 302, Taiwan, R.O.C.

Dated: Chii-Hong Li
2016/7/29

Inventor Signature

Inventor Name: Chih-Shan Chen

Residence Address: 9F., No. 101, Jixian Rd. Sanchong Dist.
New Taipei City 24151, Taiwan, R.O.C.

Dated: 7, 29, 2016

Chih-shan Chen

Inventor Signature

Inventor Name: Roger Tai

Residence Address: Tainan City, Taiwan, R.O.C.

Dated: 7, 29, 2016

Roger Tai

Inventor Signature

Docket No.: 20151406US0/24061.3342US1
Customer No.: 42717

Inventor Name: Yih-Ann Lin
Residence Address: No. 21, Lane 66, Fuguei St., Hsinchu County
Jhudong Township 310, Taiwan, R.O.C.

Dated: Yih-Ann Lin 7/29/2016
Inventor Signature

Inventor Name: Yen-Ru Lee
Residence Address: 9F., No. 539-2, Sec. 2, Jingguo Rd., North Dist.
Hsinchu City 300, Taiwan, R.O.C.

Dated: _____
Inventor Signature

Inventor Name: Tzu-Ching Lin
Residence Address: Hsinchu City, Taiwan, R.O.C.

Dated: Tzu-Ching Lin 2016 107/29
Inventor Signature

ASSIGNMENT

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- | | | | |
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| (1) | Chii-Horng Li | of | No. 137, Wencai St., Hsinchu County
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NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said

Docket No.: 20151406US0/24061.3342US1

Customer No.: 42717

invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Chii-Hong Li

Residence Address: No. 137, Wencai St., Hsinchu County
Zhubei City 302, Taiwan, R.O.C.

Dated: Chii-Hong Li
2016/7/29

Inventor Signature

Inventor Name: Chih-Shan Chen

Residence Address: 9F., No. 101, Jixian Rd. Sanchong Dist.
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Chih-shan Chen

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Inventor Name: Roger Tai

Residence Address: Tainan City, Taiwan, R.O.C.

Dated: 7, 29, 2016

Roger Tai

Inventor Signature

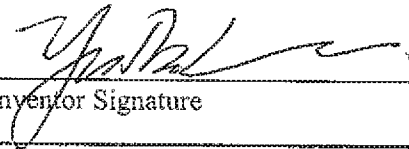
Inventor Name: Yih-Ann Lin
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Inventor Name: Yen-Ru Lee
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Dated: 07/22/2016



Inventor Signature

Inventor Name: Tzu-Ching Lin
Residence Address: Hsinchu City, Taiwan, R.O.C.

Dated: _____

Inventor Signature